

Call For Papers

SPECIAL SECTION ON ELECTROMAGNETIC COMPATIBILITY TECHNOLOGY IN CONJUNCTION WITH MAIN TOPICS OF EMC'14/TOKYO

The IEICE Transactions on Communications announces that it will publish a special section entitled "Special Section on Electromagnetic Compatibility Technology in Conjunction with Main Topics of EMC'14/Tokyo" in the **July 2015** issue.

Combining and utilizing both the wideband communication technology and the power electronics technology, such as the wireless power transfer systems and the smart meters, often cause the Electromagnetic Compatibility (EMC) problems to the function of several electronic devices. In addition, the effects on the electromagnetic environment by a natural phenomenon, which have been researched for a long time, are also problems to be solved. Therefore, the importance of the EMC technology increases not only for the functional safety of the electronic devices and systems but also for the safety between the equipment/systems and the human. Such related problems had been discussed in the 2014 International Symposium on Electromagnetic Compatibility (EMC'14/Tokyo), which had been held in Tokyo in May 2014. A special section to be issued in July 2015 is being planned in order to further promote the development of new EMC technologies. The special section solicits paper submissions from anyone associated with the EMC field and especially from people who presents paper(s) in EMC'14/Tokyo. The authors working in this field are strongly encouraged to submit original research papers on the field which include, but are not limited to, the following topics:

1. Topics

- 1) **EMC Measurements:** *Measurement & Instrumentation, Measurement Techniques, EMC Test Facilities, Antennas*
- 2) **High Power & High Voltage EMC:** *Lightning & Overvoltage Protection, Intentional EMI / EMP*
- 3) **EMC Management and Standards:** *Standards & Regulations, Electromagnetic, Product Safety, System-Level EMC, EMC Management*
- 4) **Chip, Package, PCB & Cables:** *IC EMC, Electronic Packaging, PCB, Transmission Lines & Cables, Power & Signal Integrity*
- 5) **Immunity/Susceptibility, ESD and Transients:** *EMC Tests, EM Radiation, Gap Discharge, Contact, Surge Protection*
- 6) **Shielding, Grounding & Materials:** *Shielding & Grounding, EM Absorber, Material in EMC Applications, Meta-materials*
- 7) **Numerical Modeling:** *Computational Electromagnetics, Large-scale Numerical Simulation, GPU Simulation*
- 8) **EMF Safety & Biomedical Issues:** *Human exposure to ELF/RF EM fields, Biological Effects, Medical Application*
- 9) **Power System EMC:** *Smart Grids, EMC in Power Plants & Substations, Solar Power Systems, Wireless Power Transmission*
- 10) **Power Electronics & Vehicles:** *Automotive EMC, Electric Vehicle, Railway & Naval EMC, EMC in Space*
- 11) **Communication System EMC:** *Wired & Wireless Communications, Power Line Communications, Information System Security*

2. Submission Instructions

The standard number of pages is 8. The page charges are considerably higher for extra pages. Manuscripts should be prepared according to the guideline in the "Information for Authors". The latest version is available at the web site, http://www.ieice.org/eng/shiori/mokuji_cs.html. The term for revising the manuscript after acknowledgement of conditional acceptance for this special section could be shorter than that for regular issues (60 days) because of the tight review schedule.

This special section will accept papers only by electronic submission. Submit a manuscript and electronic source files (LaTeX/Word files, figures, authors' photos and biographies) via the IEICE Web site https://review.ieice.org/regist/regist_baseinfo__e.aspx by **October 14th, 2014 (JST)**. Authors should choose the Electromagnetic Compatibility Technology in Conjunction with Main Topics of EMC'14/Tokyo as a "Journal/Section" on the online screen. Do NOT choose [Regular EB].

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